

I. Listing of Claims

1. (Currently amended): A device for cooling electronics comprising
 - (a) a container having a receptacle for receiving an electronic device, the container having an inner wall and an outer wall defining a chamber therebetween that is partially filled with a liquid coolant, wherein the receptacle is disposed between the electronic device and the chamber;
 - (b) a wick structure positioned within the container; and
 - (c) a cooling conduit defined by an outside wall having an outer surface connected with engaging the inner wall of the container for ~~receiving a cooling conduit heat transfer therebetween.~~
2. (Previously amended): The device for cooling electronics of claim 1 wherein the wick structure comprises a first wick structure lining the inside of the outer wall, a second wick structure lining the inside of the inner wall, and a communicating wick structure that periodically connects the first and second wick structures.
3. (Original): The device for cooling electronics of claim 2 further comprising at least one condenser plate positioned within the container.
4. (Original): The device for cooling electronics of claim 1 further comprising a flow divider positioned within the container opposite the receptacle.
5. (Withdrawn)
6. (Cancelled)
- 7-9. (Withdrawn)

10. (Currently amended): A method for cooling electronics comprising:

(a) providing a container having a receptacle for receiving an electronic device, the container having an inner wall and an outer wall defining a chamber therebetween; wherein the container is connected to a ~~surface for receiving~~ a cooling conduit defined by an outside wall having an outside surface engaging the inner wall for heat transfer therebetween;

(b) filling the container partially with a liquid coolant such that the liquid coolant does not contact both the inner wall and the outer wall simultaneously;

(c) providing an electronic device;

(d) connecting the electronic device to the receptacle of the container, wherein the receptacle is disposed between the electronic device and the chamber;

(e) generating heat by the electronic device;

(f) transferring heat to the coolant;

(g) connecting a cooling conduit to the container;

(h) forcing air or liquid through the cooling conduit.

11. (Original): The method of claim 10 further comprising the step of transferring the heat from vaporized coolant to the air or liquid in the cooling conduit.

12-15. (Withdrawn)

16. (Currently amended): A device for cooling electronics comprising:

(a) a container having a receptacle for receiving an electronic device, the container having an outer wall and an inner wall defining a chamber therebetween that is partially filled with a liquid coolant, wherein the receptacle is disposed between the electronic device and the chamber; and wherein the liquid coolant does not contact both the inner wall and the outer wall simultaneously; and

(b) a cooling conduit defined by an outside wall having an outer surface connected with engaging the inner wall of the container for receiving a cooling conduit heat transfer therebetween.

17. (Original): The device for cooling electronics of claim 16 wherein heat generated by an electronic device is transferred to the coolant to cause boiling of the coolant so that vaporized coolant rises away from the electronic device and substantially condenses near the inner wall of the container.

18. (Original): The device for cooling electronics of claim 16 further comprising at least one condenser plate positioned within the container.

19. (Original): The device for cooling electronics of claim 17 further comprising a wick structure capable of returning liquid coolant condensed on the inner wall toward the electronic device.

20. (Original): The device for cooling electronics of claim 16 further comprising a flow divider positioned within the chamber opposite the receptacle.

21. (Withdrawn)

22. (New): The device for cooling electronics of claim 1, further comprising a thermally conductive material interposed between the outside wall of the cooling conduit and the inner wall of the container.

23. (New): The device for cooling electronics of claim 22, wherein the thermally conductive material fills microscopic gaps between the outside wall and inner walls.

24. (New): The device for cooling electronics of claim 4, wherein the at least one condenser plate is connected to the inner wall of the container and extends radially outwardly therefrom to promote condensation at the interior of the chamber.